

07-23-2001



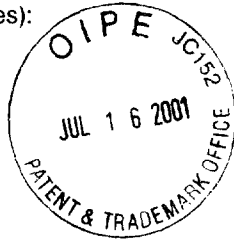
To the Honorable Commissioner of Patents and Trademarks
Please record the attached original documents or copies.

101787330

ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):
 1. Shuichi WATANABE
 2. Hideto Horiguchi
 3. Yuta SUGIYAMA
 4. Koji ICHIKAWA
 5. Hiroyuki ITOH

Additional name(s) of conveying party(ies) attached? Yes No



2. Name and address of receiving party(ies):

Name: HITACHI METALS, LTD.

Internal Address: _____

3. Nature of conveyance: 71601

Assignment Merger
 Security Agreement Change of Name

Street Address: 2-1, Shibaura 1-chome, Minato-ku
Tokyo, Japan

City: _____

State: _____ Zip Code: _____

Other

Execution Date: June 11, 2001

Additional name(s) & Address(es) attached?
 Yes No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application:

A. Patent Application Number(s): 09/816,115

B. Patent Number(s): _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington

State: DC Zip: 20005-3315

6. Total number of applications and registrations involved: 1

7. Total fee (37 CFR 3.41): \$40 /

Enclosed (Please charge deficiency to deposit account)

Authorized to be charged to deposit account

8. Deposit account number: 06-0916

9. Statement and signature.
 To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman [Signature] July 16, 2001
 Reg. No. 25,961 Signature Date

Total number of pages including cover sheet, attachments and documents: 3

07/20/2001 09:00:01 00000142 09816115
01 FC:501 40.00 DP

SOLE/JOINT INVENTION
(U.S. Rights Only)**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

NON-RECIPROCAL CIRCUIT DEVICE AND WIRELESS COMMUNICATIONS
EQUIPMENT COMPRISING SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith or on June 11 and June 18, 2001 or filed an application for United States Letters Patent on March 26, 2001 (Serial No. 09/816,115); and

WHEREAS, **HITACHI METALS, LTD.**, a corporation of Japan, whose post office address is 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

Sole or First Assignor

Full Name	Signature	Date
Shuichi WATANABE	<i>Shuichi Watanabe</i>	June 11, 2001
Address	Citizenship	
#A202, 70-1 Matoba 2-chome, Tottori-shi, Tottori-ken, Japan	Japan	

Second Assignor

Full Name	Signature	Date
Hideto HORIGUCHI	<i>Hideto Horiguchi</i>	June 11, 2001
Address	Citizenship	
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Third Assignor

Full Name	Signature	Date
Yuta SUGIYAMA	<i>Yuta Sugiyama</i>	June 18, 2001
Address	Citizenship	
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Fourth Assignor

Full Name	Signature	Date
Koji ICHIKAWA	<i>Koji Ichikawa</i>	June 11, 2001
Address	Citizenship	
701-2 Higashi-Onaricho 2-chome, Ohmiya-shi, Saitama-ken, Japan	Japan	

Fifth Assignor

Full Name	Signature	Date
Hiroyuki ITOH	<i>Hiroyuki Itoh</i>	June 11, 2001
Address	Citizenship	
14-11 Itotani, Kokufu-cho, Iwami-gun, Tottori-ken, Japan	Japan	